



US007253102B2

(12) **United States Patent**
Basceri et al.

(10) **Patent No.:** **US 7,253,102 B2**
(45) **Date of Patent:** ***Aug. 7, 2007**

(54) **METHODS FOR FORMING AND INTEGRATED CIRCUIT STRUCTURES CONTAINING ENHANCED-SURFACE-AREA CONDUCTIVE LAYERS**

(58) **Field of Classification Search** 438/650,
438/686, 381
See application file for complete search history.

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(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 142 days.

This patent is subject to a terminal disclaimer.

(21) Appl. No.: **10/860,341**

(22) Filed: **Jun. 2, 2004**

(65) **Prior Publication Data**

US 2004/0217409 A1 Nov. 4, 2004

Related U.S. Application Data

(60) Division of application No. 10/196,535, filed on Jul. 15, 2002, now Pat. No. 6,764,943, which is a continuation of application No. 09/590,791, filed on Jun. 8, 2000, now Pat. No. 6,482,736.

(51) **Int. Cl.**
H01L 21/4763 (2006.01)
H01L 21/44 (2006.01)

(52) **U.S. Cl.** **438/650**; 438/686; 257/E21.009; 257/E21.012

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